

August 26, 2026

Nidec Advance Technology to Exhibit Products at SEMICON TAIWAN 2026

Nidec Advance Technology Corporation (“Nidec Advance Technology” or the “Company”) announced today that it will exhibit products and solutions at SEMICON TAIWAN 2026, a largest international exhibition in Asia to showcase the semiconductor industry’s state-of-the-art technologies and innovations scheduled to be held at Taipei Nangang Exhibition Center (TaiNEX) from Wednesday, September 02 – Friday, September 04, 2026.



Taiwan’s most influential semiconductor-related event, SEMICON TAIWAN will be held this year under the theme “Transform Tomorrow,” by inviting more than 1,300 companies from 65 countries. At this event, under the theme, “ONE STOP SOLUTIONS of AI server/EVs,” Nidec Advance Technology will display the cutting-edge solutions of its probe cards (wafer inspection jigs), while integrating its topnotch optical and electricity inspection and probing technologies to offer inspection solutions that cover the entire semiconductor package-related processes, including wafer, chip, substrate, and package. In addition, the Company will exhibit inspection equipment and transfer robots for power semiconductors, which are in increasing demand for recent years.

About SEMICON TAIWAN 2026

- Period: Wednesday, September 02 – Friday, September 04, 2026
- Venue: Taipei Nangang Exhibition Center (TaiNEX 1)
- Booth: K3276, Hall 1

Nidec Advance Technology’s exhibit will include:

- 2D MEMS probe card for CIS/Memory
- TC probe with a measuring range from -40 to 200°C
- MEMS FLEX probe card (with a minimum pitch of 60μm, usable for cutting-edge devices)
- Chamber head probe card with a high-voltage-adaptive pressurized structure
- 40um, fine-pitch-adaptive Veri MEMS probe card
- 2,300mV, high-current-adaptive vertical high-current probe card
- GATS®-7886 (high-precision conduction inspection system for FOPLP/RDL)
- GATS®-7837 high-precision conduction inspection system for large, individual-piece semiconductor packages)
- GATS®-8370 (full-panel multi-unit inspection system for semiconductor packages)
- NS probe (a narrow-pitch-adaptive jig solution)
- RWi series (wafer-bump-adaptive optical 2D/3D inspection system)

- RSH series (high-density-substrate-adaptive 2D/3D inspection system)
- AURCA Series (optical-module- and large-substrate-adaptive, next-generation AI visual inspection system)
- High-precision inspection solution for TGV (Through Glass Via)
- AVR SMV 3000 (a wafer transfer robot system) *Jointly developed with Nidec Instruments Corporation

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